

Form PTO-1449 (Rev. 8-83) U.S. Department of Commerce Patent and Trademark Office <b>INFORMATION DISCLOSURE STATEMENT</b> (Use several sheets if necessary)		Attorney Docket No. 0756-1630		Serial No. 08/799,506		
		Applicant: Shunpei YAMAZAKI et al.				
		Filing Date: February 12, 1997		Group: 1107		
<b>U.S. PATENT DOCUMENTS</b>						
Examiner Initial	Document Number	Date	Name	Class	Subclass	
MW	5,028,560	07/02/91	Tsukamoto et al	437	239	
MW	5,322,807	06/21/94	Chen et al	437	41TFT	
MW	5,298,436	03/29/94	Radosevich et al	437	233	
MW	5,294,571	03/15/94	Fujishiro et al	437	239	
MW	4,675,978	06/30/87	Swartz	437	21	
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MW	5,412,493	05/02/95	Kunii et al	437	41TFT	
MW	5,147,826	09/15/92	Liu et al	437	233	
MW	5,372,958	12/13/94	Miyasaka et al	437	40	
MW	5,663,077	09/02/97	Adachi et al			
<b>FOREIGN PATENT DOCUMENTS</b>						
	Document Number	Date	Country	Class	Subclass	Translation Yes      No
MW	3-289140	12/19/91	Japan	437	21	Abstract
MW	53-26584	03/11/78	Japan	437	21	Abstract
MW	4-102375	04/03/92	Japan	437	41TFT	X
MW	04-251921	09/08/92	Japan			Abstract
MW	03-82121	04/08/91	Japan			Abstract
MW	05-206063	08/13/93	Japan			Abstract
<b>OTHER DOCUMENTS</b> (Including Author, Title, Date, Pertinent Pages, Etc.)						
MW	S. Wolf, "Silicon Processing for the VLSI Era, Vol. 1: Process Technology" Lattice Press, January 1986, pp. 57-58					RECEIVED
MW	S. Wolf et al., "Silicon Processing for the VLSI Era, Vol 3: The Submicron Effect" Lattice Press, California, October 1985, pp. 502-504					AUG 12 1998
MW	J. Nulman et al., "Rapid Thermal Processing of Thin Gate Dielectrics" IEEE Electron Device Letters, Vol. 6, No. 5, pp. 205-207, May 1985					GROUP 200
MW	United States Defense Publication T954,009 (Malin et al.), "Method for the Thermal Oxidation of Silicon with Added Chlorine," January 4, 1977					
Examiner	MWilczewski		Date Considered	9/2000		
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